

Mag Layers USA, INC

Specification Sheet

P/N: MMD-06EZ-M1-Series-RU

Products:

Certifications:

Molded Power Chokes

Multilayer Chip Inductors

Lan Transformer

RF Passive / Antennas

<u>Automotive</u>

<u>ISO9001</u>

IATF16949

ISO14001

QC080000

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Product Specification		Part Number: MMD-06E	Z-R15M-M1-LT	SPEC.NO. 11005469				
	REVISIONS							
REV.	DESCIPTION	DATE	Approved By	Checked By	Made By			
01	Final release	2011/10/27	Richard	Jerry CH	Sophia			





PDA, notebook, desktop, and server application_S Low profile, high current power supplies Battery powered devices DC/DC converters in distributed power systems DC/DC converters for field programmable gate array

FEATURES

RoHS compliant Super low resistance, ultra high current rating High performance (I sat) realized by metal dust core Frequency Range: up to 1MHz

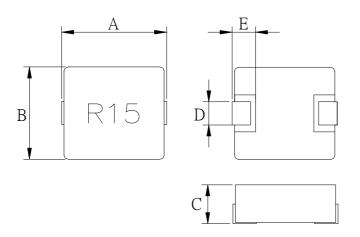
PRODUCT IDENTIFICATION

① ② ③ ④ ⑤ MMD - <u>06EZ</u> - <u>R15 M</u> - <u>M1</u> - <u>RU</u>

- ① Product Code
- ② Dimensions : 6.8 x 6.4 x 5.0 mm
- ③ Inductance : R15 = 0.15 μ H
- ④ Tolerance : $M = \pm 20\%$
- (5) Series Type : M1 Type



PRODUCT DIMENSION



 $\mathsf{NOTE}:\mathsf{Dimensions}\;\mathsf{in}\;\mathsf{mm}$

PRODUCT NO.	А	В	С	D	E
MMD-06EZ-R15M-M1-RU	6.86 ± 0.38	6.47 ± 0.25	5.0Max	3.0 ± 0.3	1.3 ± 0.3

ELECTRICAL REQUIREMENTS

PART NUMBER	INDUCTANCE Lo(μ H)±20% @0A	(HEAT RATING CURRENT(Idc) DC AMPS ¹	SATURATION CURRENT(Isat) DC AMPS ²
MMD-06EZ-R15M-M1-RU	0.15	0.80	0.88	28	41

TEST FREQUENCY:100KHz,0.25V

TESTING INSTRUMENT L :Agilent4284A,WK4235,CH3302/G LCR METER CH1320,CH1320S BIAS CURRENT SOURCE Rdc :CH11025,GOM802 MICRO OHMMETER

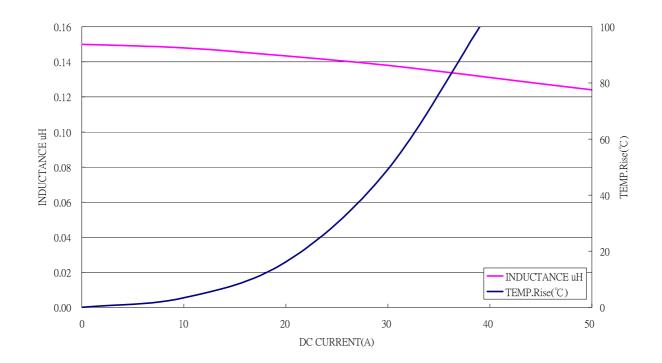
NOTES:

- 2. DC current (Isat) that will cause Lo to drop approximately 20%
- 3. All test data is referenced to $25^\circ\!\!\mathbb{C}$ $\,$ ambient
- 4. Operating Temperature Range $~-55^\circ\!\mathrm{C}$ to $+150^\circ\!\mathrm{C}$
- 5. The part temperature (ambient + temp rise) should not exceed 150°C under the worst operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.



Reference data

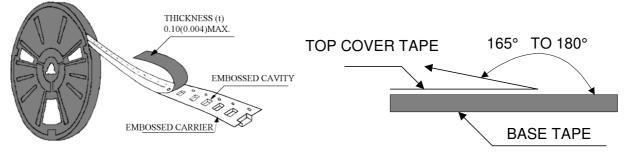
ELECTRICAL CHARACTERISTICS



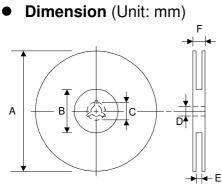




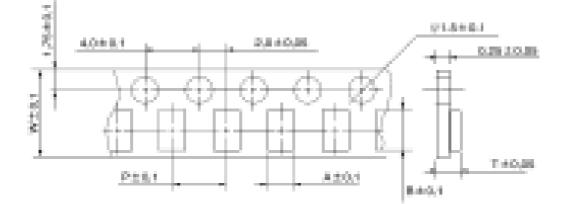
Peel-off Force



The force for peeling off cover tape is 10 to 70 grams in the arrow direction.

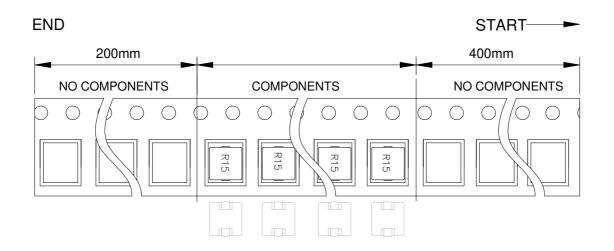


TYPE	A	В	С	D	E	F
330 mm	330±2	100±1	20±0.5	13 ±1.0	16 ±0.5	20 ±2



TYPE	SIZE	А	В	W	Р	Т
MMD	06EZ	6.9	7.6	16	12	5.3

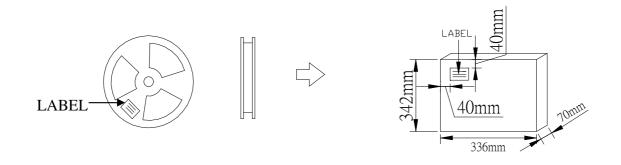




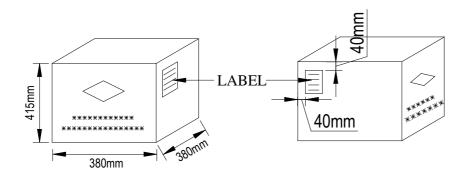
Taping Quantity

SERIES	06EZ	
PCS/Reel	500	

CARTON: MIDDLE PACKAGING : 3 Reel /BOX

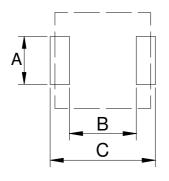


EXTERNAL PACKAGING : 5 BOX / CARTON





RECOMMENDED PCB LAYOUT



Туре	06EZ
А	3.43
В	3.71
С	7.37

Safety precaution

- (A) This product employs a core with low insulation resistance. Pay strict attention when use it.
 - 1. Do not make any through holes and copper pattern in the oblique line area. Except a copper pattern to the electrode.
 - 2. Don't design/mount any components in contact with this product.
- (B) Provision to abnormal condition

This power choke coil itself does not have any protective function in abnormal condition such as overload, short circuit, open conditions and etc. Therefore, it shall be confirmed as the end product that there is no risk of smoking, fire, dielectric withstand voltage, insulation resistance and etc in abnormal conditions to provide protective devices and/or protection circuit in the end product.



RELIABILTY TEST

*Electrical perfo	*Electrical performance test					
Item	Specification	Test method				
Inductance		Measured with a LCR meter Agilent4284A,CH3302G				
DC Resistance		Micro-ohm meter CH11025				
Saturation current	Refer to the electrical specifications.	DC current (A) that will cause L0 to drop approximately 30% (environment temperature of $25^{\circ}C$)				
Heat rating current		DC current (A) that will cause an approximate $\triangle T$ of 40°C (environment temperature of 25°C)				
*Mechanical per	formance test					
bending	Change from an initial value Inductance: within ± 10%	Apply pressure gradually in the direction of the arrow at a rate of about 0.5mm/s until bent depth reaches 2mm and hold for 30 sec. Boad : 40*100mm , thickness: 1mm				
Adhesion strength	Change from an initial value Inductance: within ± 10%	A static load using a R0.5 pressing tool shall be applied to the body of the specimen in the direction of the arrow and shall be hold for 60±5 sec. Mesure after removing pressure.				
Vibration	Change from an initial value Inductance: within ± 10%	The specimen shall be subjected to a vibration of 1.5mm amplitude, sweep frequency 10~55Hz(10Hz to 55Hz to 10Hz in aperiod of one minute) for 2hr in each of 3(X,Y,Z) axes.				
Mechanical shock	Change from an initial value Inductance: within ± 10%	Dropped onto printed circuit board from 100cm height three times in x, y, z directions. The terminals shall be protected.				

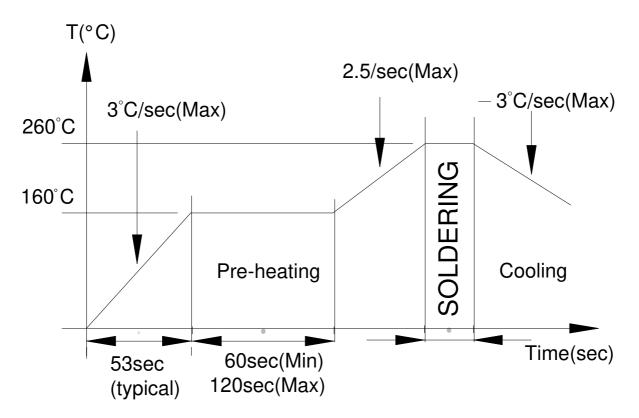


Item	Specification	Test method
	New solder shall cover 90%	Electrode shall be immersed in flux at room temperature
a a baba wa la 114a y	minimum of the surface	and then shall be immersed in solder bath after preheat.
solderability	immersed.	Preheat 160±10℃, 90 sec
		Soldering 245±5℃ , 3±1 sec
		Reflow soldering method
		Preheat 150~180℃,90~120sec
		Peak temp. 260℃ (230℃ over 30~40 Sec.)
		The specimen shall be subjected to the reflow process
		under the above condition 2 times. Test board shall be
Resistance to	Change from an initial value	0.8mm thick. Base material shall be glass epoxy resin.
solldering heat	Inductance: within ± 10%	Soldering iron method
Ū		Bit temperature 230± 7°C
		Period of soldering 3sec
		Measurement
		The specimen shall be stored at standard atmospheric
		conditions for 1 hr in prior to the measurement.
*Climatic test	1	
		The specimen shall be stored at a temperature of -40±3°C
	Change from an initial value	for 96hr. then it shall be stabilized under standard
Low temperature	Inductance: within $\pm 10\%$	atmospheric conditions for 1hr before measurement.
		measurement shall be made within 1hr.
		The specimen shall be stored at a temperature of $85\pm3^{\circ}$ C
	Change from an initial value	for 96hr. then it shall be stabilized under standard
Dry heat	Inductance: within ± 10%	atmospheric conditions for 1hr before measurement.
		measurement shall be made within 1hr.
		The specimen shall be stored at a temperature of $60\pm3^\circ\text{C}$
		with relative humidity of 90~95% for 96h. Then it shall be
Dump heat	Change from an initial value	stabilized under standard atmospheric conditions for 1hr
	Inductance: within ± 10%	before measurement. Measurement shall be made within
		1hr.
		The specimen shall be subjected to 10 continuous cycles
Temperature cycle	C C	
	Inductance: within ± 10%	
		shall be made within 1hr.
Temperature cycle	Change from an initial value Inductance: within ± 10%	1hr. The specimen shall be subjected to 10 continuous cycles of temperature change of -40° C for 30 min and 85° C for 30 min with the transit period of 2 min or less. Then it shall be stabilized under standard atmospheric conditions for 1hr before measurement. Measurement

NOTE : Storage Condition : The temperature should be within -40° C $\sim 85^{\circ}$ C and humidity should be less than 75%RH. The product should be used within 6 months from the time of delivery.



RECOMMENDED REFLOW SOLDERING PROFILE



1. IR Reflow soldering :

Preheat at 3 $^\circ\!{\rm C}\,$ per second to 160 $^\circ\!{\rm C}\,$ and using lead free solder , IR at 260 $^\circ\!{\rm C}\,$ $\,$ for 10 seconds.

2. Rework flow:

Component must withstand two IR reflow cycles with a cool down between cycles.



The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

